

General Description

The QM3018D is the highest performance trench N-ch MOSFETs with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The QM3018D meet the RoHS and Green Product requirement , 100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^{1,7}$	155	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^{1,7}$	110	A
I_{DM}	Pulsed Drain Current ²	310	A
EAS	Single Pulse Avalanche Energy ³	378	mJ
I_{AS}	Avalanche Current	70.2	A
$P_D @ T_C = 25^\circ C$	Total Power Dissipation ⁴	89.3	W
T_{STG}	Storage Temperature Range	-55 to 175	°C
T_J	Operating Junction Temperature Range	-55 to 175	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	---	62	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	1.4	°C/W

Product Summary

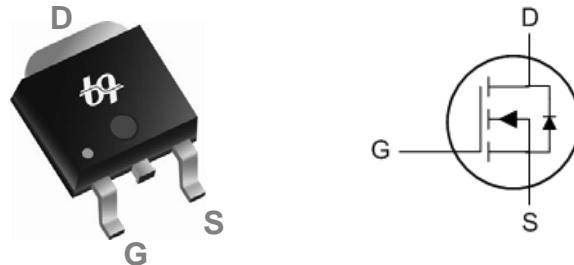


BVDSS	RDS(on)	ID
30V	3mΩ	155A

Applications

- High Frequency Point-of-Load Synchronous Buck Converter
- Networking DC-DC Power System
- Power Tool Application

TO252 Pin Configuration



Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_D=250\mu\text{A}$	30	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $\text{I}_D=1\text{mA}$	---	0.022	---	$\text{V}/^\circ\text{C}$
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance ²	$\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=30\text{A}$	---	2.4	3	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=15\text{A}$	---	3.2	4	
$\text{V}_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}$, $\text{I}_D=250\mu\text{A}$	1	1.5	2.5	V
$\Delta \text{V}_{\text{GS}(\text{th})}$	$\text{V}_{\text{GS}(\text{th})}$ Temperature Coefficient		---	-6.1	---	$\text{mV}/^\circ\text{C}$
I_{DSS}	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=24\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	2	uA
		$\text{V}_{\text{DS}}=24\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $T_J=55^\circ\text{C}$	---	---	10	
I_{GSS}	Gate-Source Leakage Current	$\text{V}_{\text{GS}}=\pm 20\text{V}$, $\text{V}_{\text{DS}}=0\text{V}$	---	---	± 100	nA
gfs	Forward Transconductance	$\text{V}_{\text{DS}}=5\text{V}$, $\text{I}_D=30\text{A}$	---	60	---	S
R_g	Gate Resistance	$\text{V}_{\text{DS}}=0\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	0.9	1.8	Ω
Q_g	Total Gate Charge (4.5V)	$\text{V}_{\text{DS}}=15\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=15\text{A}$	---	56.9	---	nC
Q_{gs}	Gate-Source Charge		---	13.8	---	
Q_{gd}	Gate-Drain Charge		---	23.5	---	
$\text{T}_{\text{d}(\text{on})}$	Turn-On Delay Time	$\text{V}_{\text{DD}}=15\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $\text{R}_g=3.3\Omega$, $\text{I}_D=1\text{A}$	---	20.1	---	ns
T_r	Rise Time		---	6.3	---	
$\text{T}_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	124.6	---	
T_f	Fall Time		---	15.8	---	
C_{iss}	Input Capacitance	$\text{V}_{\text{DS}}=15\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	5935	---	pF
C_{oss}	Output Capacitance		---	725	---	
C_{rss}	Reverse Transfer Capacitance		---	538	---	

Guaranteed Avalanche Characteristics

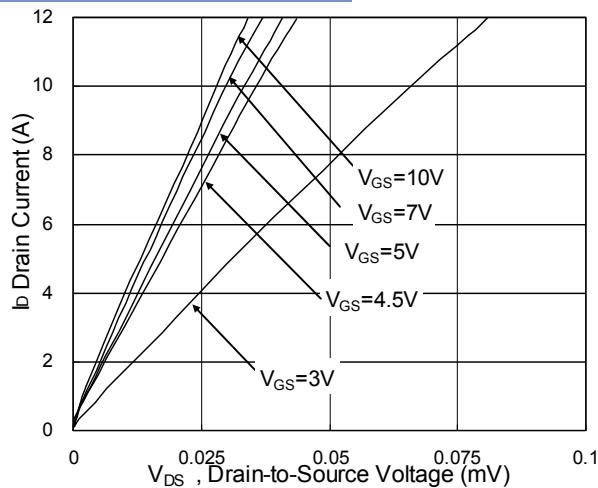
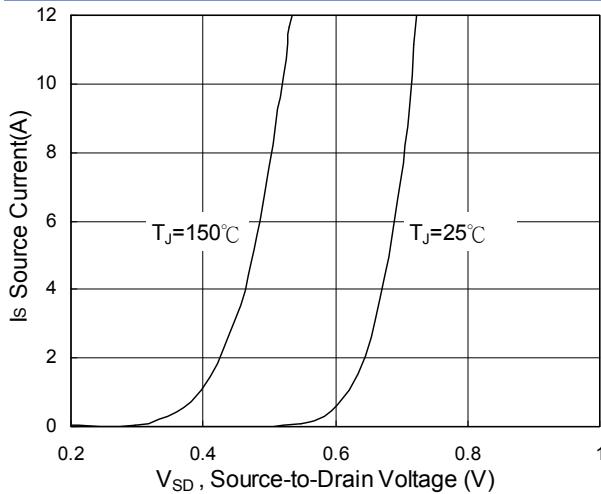
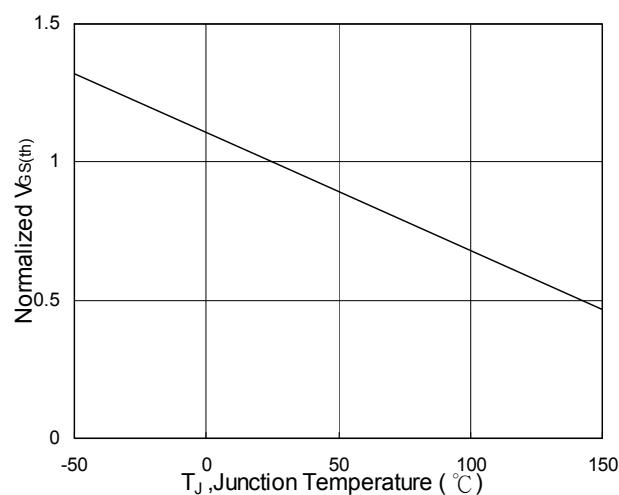
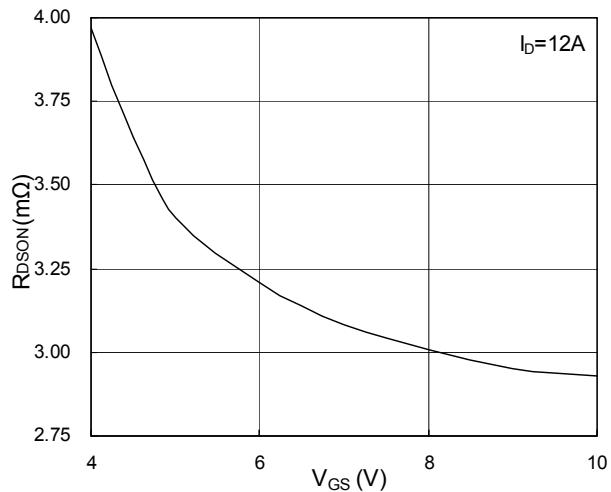
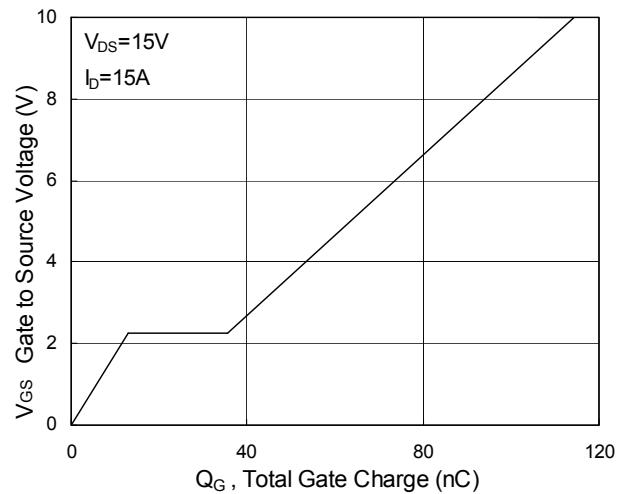
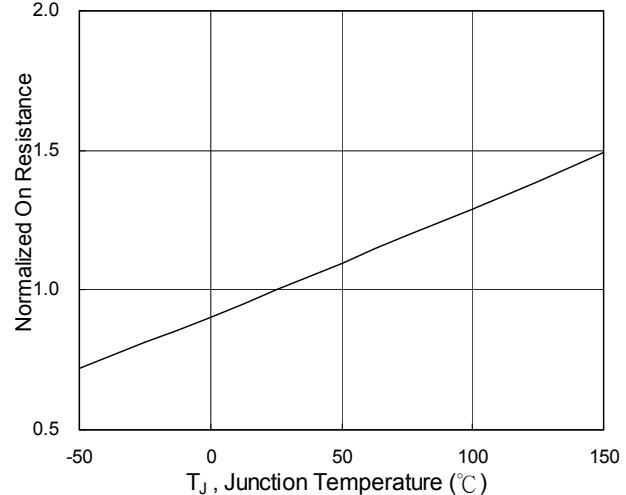
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
EAS	Single Pulse Avalanche Energy ⁵	$\text{V}_{\text{DD}}=25\text{V}$, $\text{L}=0.1\text{mH}$, $\text{I}_{\text{AS}}=30\text{A}$	69	---	---	mJ

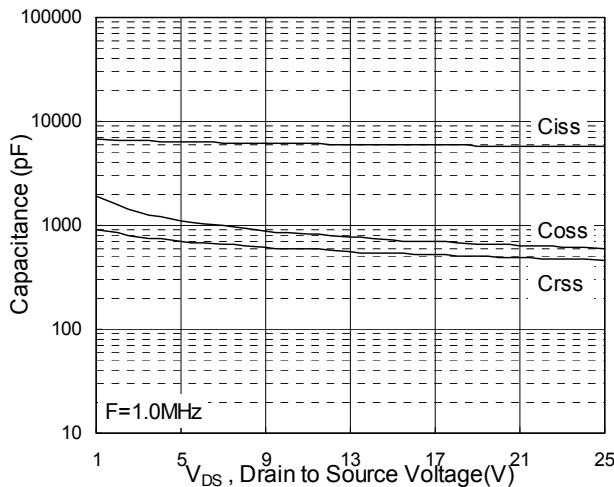
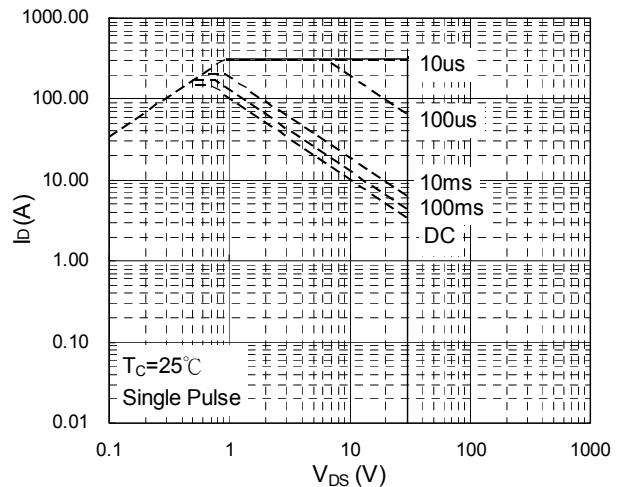
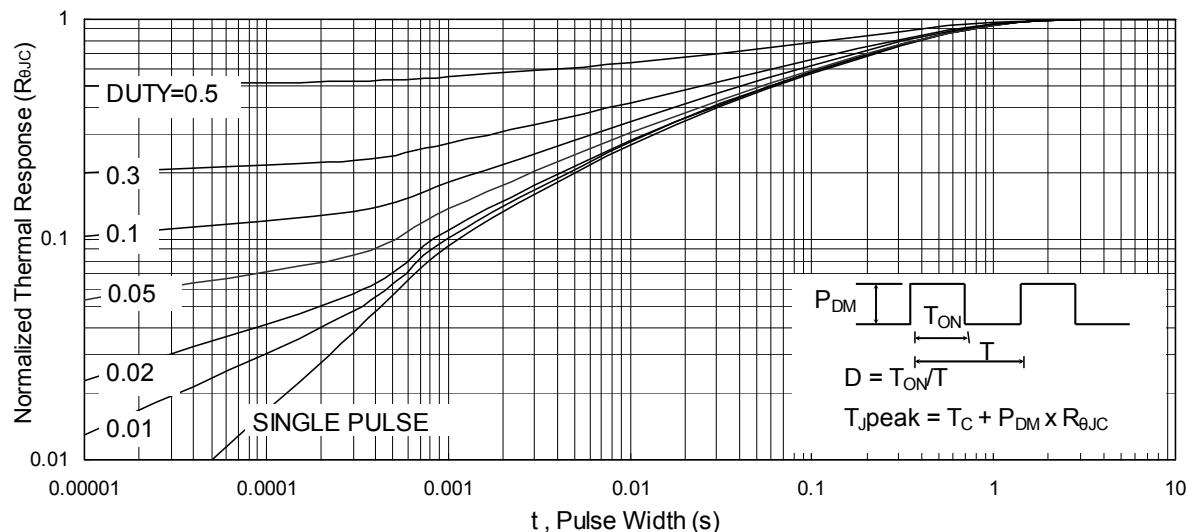
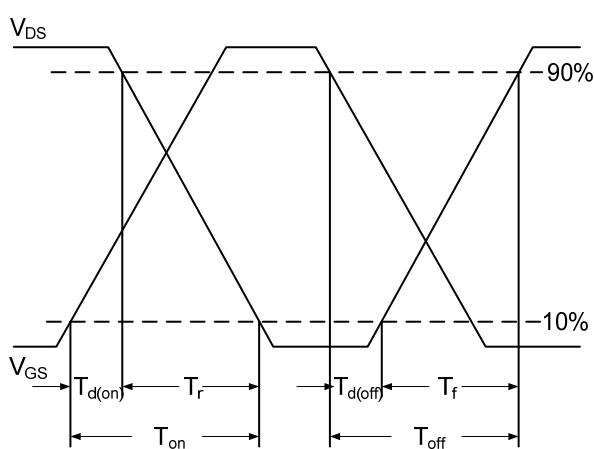
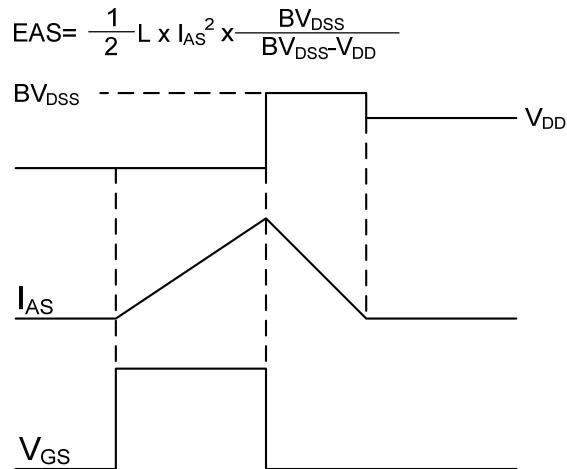
Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current ^{1,6}	$\text{V}_G=\text{V}_D=0\text{V}$, Force Current	---	---	155	A
I_{SM}	Pulsed Source Current ^{2,6}		---	---	310	A
V_{SD}	Diode Forward Voltage ²	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_S=A$, $T_J=25^\circ\text{C}$	---	---	1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $\text{V}_{\text{DD}}=25\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $\text{L}=0.1\text{mH}$, $\text{I}_{\text{AS}}=70.2\text{A}$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The Min. value is 100% EAS tested guarantee.
- 6.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.
- 7.Package limitation current is 85A.

Typical Characteristics

Fig.1 Typical Output Characteristics

Fig.3 Forward Characteristics of Reverse

Fig.5 Normalized $V_{GS(\text{th})}$ v.s T_J

Fig.2 On-Resistance v.s Gate-Source

Fig.4 Gate-Charge Characteristics

Fig.6 Normalized R_{DSON} v.s T_J

N-Ch 30V Fast Switching MOSFETs

Fig.7 Capacitance

Fig.8 Safe Operating Area

Fig.9 Normalized Maximum Transient Thermal Impedance

Fig.10 Switching Time Waveform

Fig.11 Unclamped Inductive Waveform